

NOTES:

1.MATERIAL:

HOUSING: HIGH TEMPERATURE NYLON , HALOGEN FREE, GLASS FILLED UL94V-0 RATED.

TERMINAL: COPPER ALLOY.

PLATING: SEE PRODUCT NUMBER CODE METAL BOARD LOCKS: COPPER ALLOY. 2.PRODUCT SPECIFICATION: GS-12-233.

PACKAGING SPECIFICATION: GS-14-858 FOR SOFT TRAY, TAPE AND REEL, GS-14-1451 FOR HARD TRAY.

(3)THE HORIZONTAL AXIS FOR THE HOLE PATTERN IS ESTABLISHED BY

A LINE THROUGH THE CENTER OF THE TWO Ø2.35 HOLES.

THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS. THROUGH THE CENTER OF DATUM Z.

(4)NO TIE BAR PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1 AND PIN NUMBERS "F". (5) CHAMFER EDGES MUST BE FREE OF CUTTING BURRS.

(6) FREQUENCY & LOCATION AT SUPPLIER DISCRETION. RIDGE MAY BE CONTINUOUS WITH NO BREAKS.

7.RoHS COMPATIBLE PRODUCT SPECIFICATIONS:

a - PLATING:

- "LF" MEANS THE PRODUCT IS LEAD-FREE, 2um MINIMUM MATTE TIN OVER 1.27um MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY:

- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 5 SECONDS IN RE-FLOW APPLICATIONO.

CONNECTOR	# POS REF.	N	DIM "A"	DIM "B"	DIM "C"	"E"
1 PORT	36	6	7.65	25.00	9.15	6.00
4 PORT	64	20	21.65	39.00	23.15	20.00
8 PORT	98	37	38.65	56.00	40.15	37.00
16 PORT	164	70	71.65	89.00	73.15	70.00

8.AN ADEQUATE PROCEDURE SET FORTH IN THE FOLLOWING ENSURE THAT THE PRODUCT RELIABILITY CAN BE ACHIEVED DURING AND AFTER PCB ASSEMBLY OPERATION.

8.11F PARTIAL LOT ARE USED. THE REMAINING CONNECTORS MUST BE RESEALED AND PLACED IN SAFE STORAGE WITHIN SIX HOURS OF BAG OPENING.

8.2THE SAFE STORAGE CONDITION IS RECOMMENDED AT 25°C, 40%RH.

8.3NOT FOLLOWING THE PROCEDURE MAY CAUSE BLISTER DAMAGE DURING RE-FLOW PROCESS.

8.4IF BAKING IS REQUIRED, CONNECTOR SHALL BE BAKED FOR 4 HOURS AT 125°C.

8.5REFERENCE SPECIFICATION: IPC/JEDEC J-STD-033A.

PRODUCT NUMBER CODE 10138327 -x x x x x x LF

HOUSING COLOR OPTIONS

0-NATURAL 1-BLACK 2-DEEP BLUE

PEGS OPTIONS

0-PLASTIC PEGS 1-METAL BOARD LOCKS 2-SINGLE PLASTIC PEGS

TERMINAL PLATING OPTIONS

0-50u" Ni UNDERPLATE 30u" Au CONTACT AREA

100u" TIN TAIL AREA ---- COMPATIBLE RoHS

1-50u" Ni UNDERPLATE 15u" Au CONTACT AREA

100u" TIN TAIL AREA ---- COMPATIBLE RoHS

2-50u" Ni UNDERPLATE GOLD FLASH CONTACT AREA

100u" TIN TAIL AREA ---- COMPATIBLE RoHS

LEAD FREE OPTION

POS OPTIONS

0 - 36

1 - 64

2-98

3-164

PACKAGING OPTIONS

E-HARD TRAY WITH MYLAR (640PCS PER CARTON)

T-SOFT TRAY PACKAGING C-SOFT TRAY PACKAGING WITH 10MM CAP

M-SOFT TRAY PACKAGING & MYLAR TAPE. SEE FIGULE 1

Y-HARD TRAY PACKAGING

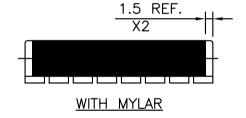
Z-HARD TRAY PACKAGING WITH MYLAR

Q-SMALLER HARD TRAY WITHOUT CAP (323x136x19 FOR 164P ONLY)

R-TAPE & REEL PACKAGING WITHOUT MYLAR (FOR 36, 64, 98P)

W-TAPE & REEL PACKAGING WITHOUT MYLAR (FOR 98P ONLY), WITH 18.0MM CAVITY WIDTH

A-TAPE & REEL PACKAGING WITH MYLAR(FOR 36, 64, 98P)



TAIL LENGTH OPTIONS

	DIM "D"	PCB THICKNESS	BOARD LOCKS DIM "G"
0	2.30 +0.25	1.56±0.10	1.70
1	3.10 +0.25	2.36±0.10	2.50
2	2.54±0.25	1.56±0.10	1.70
3	1.90±0.25	1.56±0.10	1.70
4	3.10 +0.25	2.0±0.10	1.70

mat'l. code /tolerance surface projection product family PCI EXPRESS ASME_Y14.5 tolerances unless otherwise specified title |ltr|ecn no|dr|date .0±.0.30 MM PCI_EXPRESS_CARD_EDGE_GEN3 angles a .00±.0.20 ASSEMBLY(TH) ±2. .000±.0.10 scale N/A ZHENHUA_LIU 2020-07-07 dwg no sheet 6 of 6 size engr zhenhua_Liu 2020-07-07 Ampheno 10138327 appd heaven_cen | 2020-07-07

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CUSTOMER Drawing type

form: A4mmXLc-2016-02-24

В

STATUS:Released

Isheet

index

revision C

sheet

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